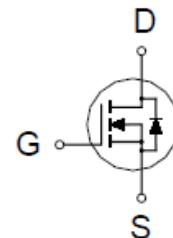
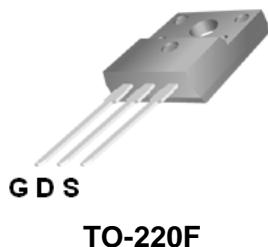


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N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
500V	0.85Ω @ $V_{GS} = 10V$	8A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	500	V
Gate-Source Voltage	V_{GS}	± 30	
Continuous Drain Current ²	I_D	8	A
		5	
Pulsed Drain Current ^{1,2}	I_{DM}	30	
Avalanche Current ³	I_{AS}	6.8	
Avalanche Energy ³	E_{AS}	232	mJ
Power Dissipation ^A	P_D	39	W
		15.6	
Operating Junction & Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Limited only by maximum temperature allowed.

³ $V_{DD} = 50V$, Starting $T_J = 25^\circ C$

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	500			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.5		4.5	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 30\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 500\text{V}, V_{\text{GS}} = 0\text{V}, T_C = 25^\circ\text{C}$			25	μA
		$V_{\text{DS}} = 500\text{V}, V_{\text{GS}} = 0\text{V}, T_C = 100^\circ\text{C}$			250	
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 4\text{A}$		0.65	0.85	Ω
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 20\text{V}, I_D = 4\text{A}$		7		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$		1250		pF
Output Capacitance	C_{oss}			138		
Reverse Transfer Capacitance	C_{rss}			14		
Total Gate Charge ²	Q_g	$V_{\text{DS}} = 250\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 4.8\text{A}$		21.6		nC
Gate-Source Charge ²	Q_{gs}			7.2		
Gate-Drain Charge ²	Q_{gd}			6.6		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 250\text{V}, I_D = 4.8\text{A}, R_G = 25\Omega$		23		nS
Rise Time ²	t_r			71		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$			112		
Fall Time ²	t_f			69		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current ³	I_S				8	A
Forward Voltage ¹	V_{SD}	$I_F = 4\text{A}, V_{\text{GS}} = 0\text{V}$			1.7	V
Reverse Recovery Time	t_{rr}	$I_F = 4.8\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}, V_{\text{GS}} = 0\text{V}$		480		nS
Reverse Recovery Charge	Q_{rr}			5		nC

¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

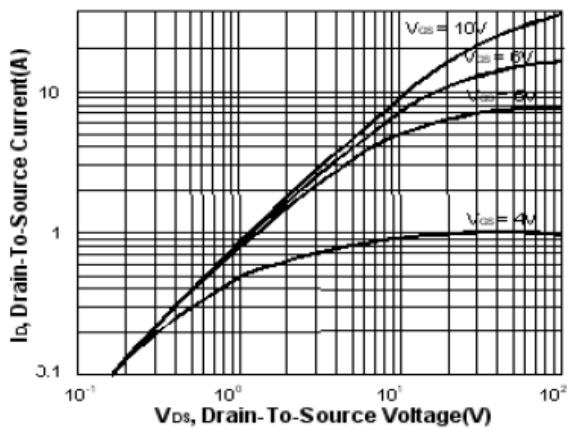
²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

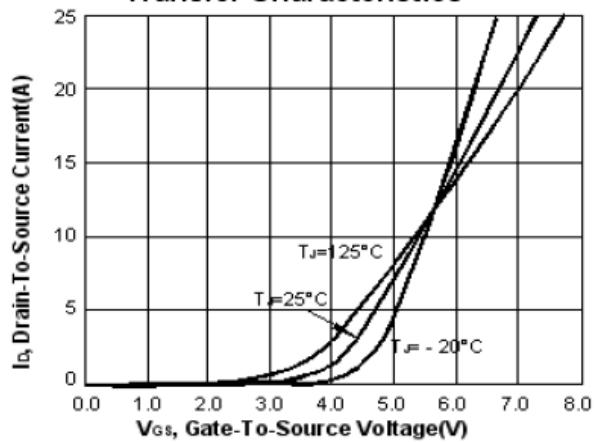
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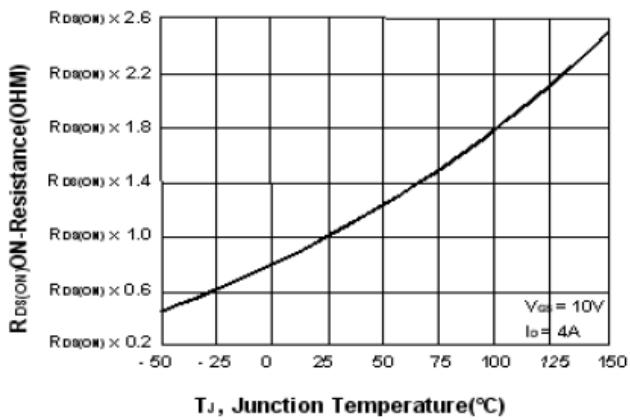
Output Characteristics



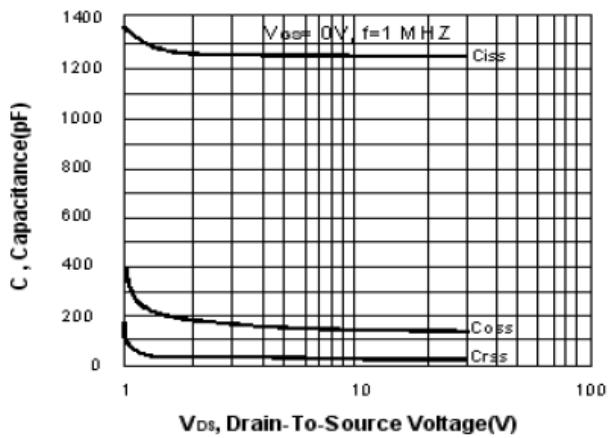
Transfer Characteristics



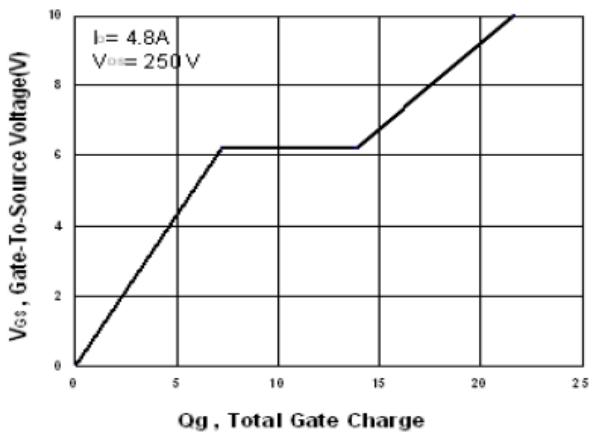
On-Resistance VS Temperature



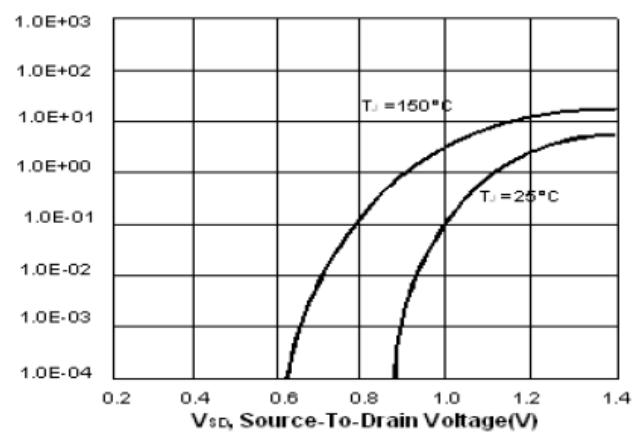
Capacitance Characteristic



Gate charge Characteristics

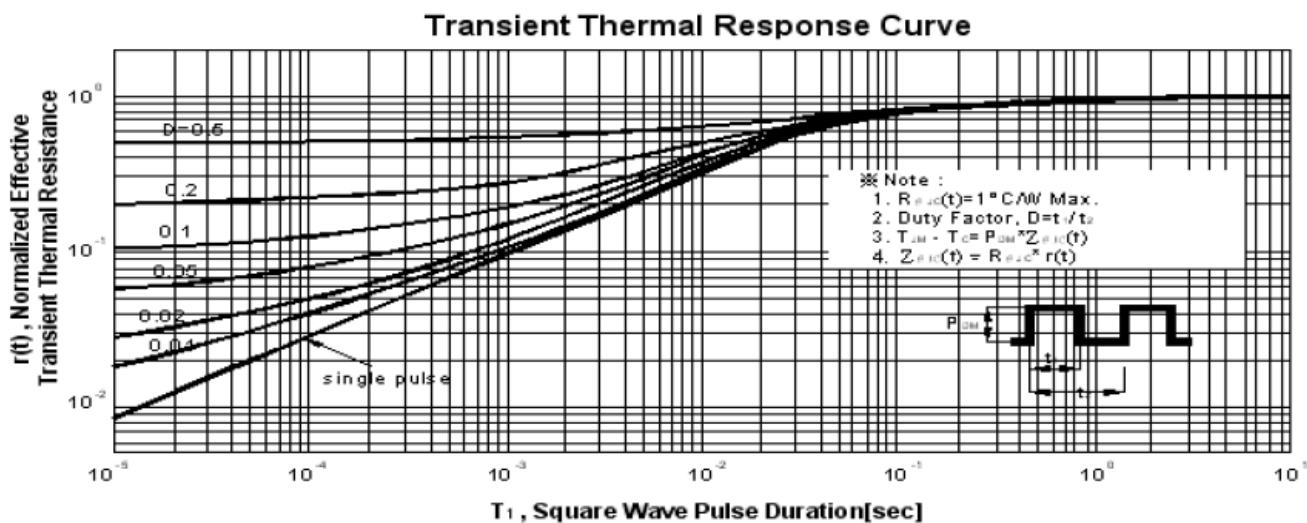
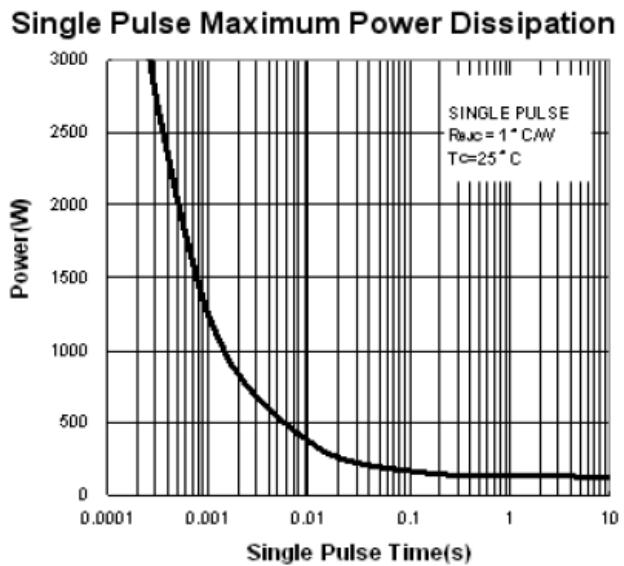
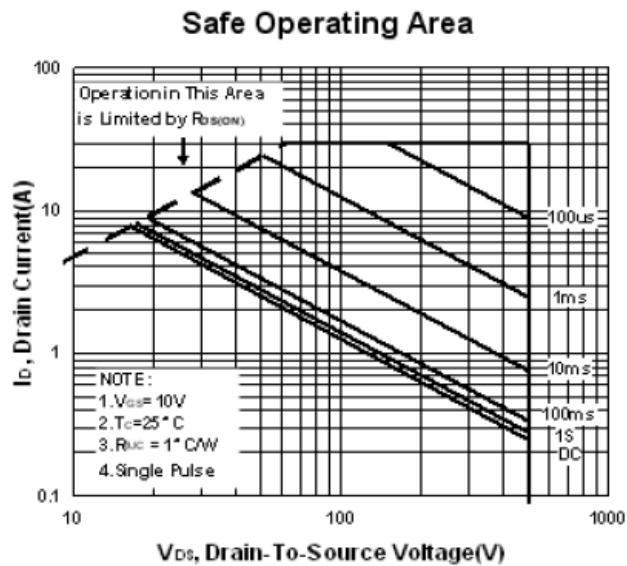


Source-Drain Diode Forward Voltage



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Package Dimension

TO-220F (3-Lead) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.2		4.93	e	2.05	2.55	3.05
A1	2.34		3.1	F	27.45		30.6
B	17.77		20.3	G	7.72		9.3
b	0.6		1.05	H	6.1		7.1
b1	0.9	1.23	1.62	L	12.5		14.5
b2	0.6		1.9	L1	1.97		3.8
c	0.4		1.0	P	2.98		3.4
D	14.7		16.4	Q	2.1		2.96
D1	6.4		7.5	q	3.0		3.8
E	9.7		10.4				

